This Sheet Has Been Replaced



ABSTRACT OF THE DISCLOSURE

A holder driving mechanism holds a wafer holder with gripping portions, and swings it within a wafer processing bath. When the peripheral portion of a wafer comes into contact with the distal end portion of a swing support member, the wafer rotates and vertically moves in the wafer holder. The wafer can be efficiently swung, and processing can be made uniform. By supplying ultrasonic waves from an ultrasonic bath, the processing rate can be increased.